



BTE-040-02-L-D-A

BTE-060-02-F-D-A

(0,80 mm) .0315"

BTE, BSE SERIES

BASIC BLADE & BEAM HEADER & SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?BTE or www.samtec.com?BSE

Insulator Material: Liquid Crystal Polymer
Contact Material: Phosphor Bronze
Plating: Au or Sn over 50µ" (1,27 µm) Ni
Current Rating: 2A/Contact @ 80°C ambient with 5 mm Stack Height
Operating Temp Range: -55°C to +125°C
Voltage Rating: 225 VAC with 5 mm Stack Height
Max Cycles: 100
RoHS Compliant: Yes



Processing: Lead-Free Solderable: Yes

SMT Lead Coplanarity: (0,10 mm) .004" max (020-080) (0,15 mm) .006" max (100-120)
Board Stacking: For applications requiring more than two connectors per board or 80 positions or higher, contact ipg@samtec.com

BTE - **NO. OF POSITIONS PER ROW** - **LEAD STYLE** - **PLATING OPTION** - **D** - **A** - **OTHER OPTION**

Mates with: BSE

-020, -040, -060, -080, -100, -120

Specify LEAD STYLE from chart

LEAD STYLE	A
-01	(4,27) .168
-02	(7,21) .284

-F = Gold Flash on contact, Matte Tin on tail
-L = 10µ" (0,25 µm) Gold on contact, Matte Tin on tail
-C* = Electro-Polished Selective 50µ" (1,27 µm) min Au over 150µ" (3,81 µm) Ni on Signal Pins in contact area, 10µ" (0,25 µm) min Au over 50µ" (1,27 µm) Ni on Ground Plane in contact area, Matte Tin over 50µ" (1,27 µm) min Ni on all solder tails

-K = (7,00 mm) .275" DIA Polyimide Film Pick & Place Pad
-TR = Tape & Reel (60 positions maximum)



MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
-01	(5,00) .197
-02	(8,00) .315

*Processing conditions will affect mated height.

BSE - **NO. OF POSITIONS PER ROW** - **01** - **PLATING OPTION** - **D** - **A** - **OTHER OPTION**

Mates with: BTE

-020, -040, -060, -080, -100, -120

-F = Gold Flash on contact, Matte Tin on tail
-L = 10µ" (0,25 µm) Gold on contact, Matte Tin on tail
-C* = Electro-Polished Selective 50µ" (1,27 µm) min Au over 150µ" (3,81 µm) Ni on Signal Pins in contact area, 10µ" (0,25 µm) min Au over 50µ" (1,27 µm) Ni on Ground Plane in contact area, Matte Tin over 50µ" (1,27 µm) min Ni on all solder tails

-TR = Tape & Reel (80 positions maximum)

APPLICATION SPECIFIC

- 30µ" (0,76 µm) Gold
- Edge Mount Capability
- Friction Lock option
- 11 mm, 14 mm, 16,10 mm, 19,10 mm, 22 mm, 25 mm and 30 mm Stack Height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.) Call Samtec.

*Note: -C Plating passes 10 year MFG testing

Note: Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM